



Ansys Receives Two TSMC Open Innovation Platform Partner of the Year Awards

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Ansys receives awards for Joint Development of 3nm Design Infrastructure and Joint Development of 3D-IC Design Productivity Solution

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TSMC_fabrication_operator_examining

/ Key Highlights

- Ansys secured an award in the category of Joint Development of 3nm Design Infrastructure for delivering foundry-certified, state-of-the-art power integrity and electromigration signoff verification tools for TSMC's 3nm process technology
- Ansys earned an award in the category of Joint Development of 3D-IC Design Productivity Solution for providing a foundry-certified advanced semiconductor design for TSMC's 3D-IC advanced packaging technologies

[TSMC](#) awarded [Ansys](#) (NASDAQ: ANSS) two Open Integration Platform (OIP) Partner of the Year awards. Ansys' multiphysics simulation solutions for TSMC's world-class 3nm process and highly sophisticated three-dimensional integrated circuit (3D-IC) advanced packaging technologies help mutual customers speed the design of smartphone, high-performance computing, automotive and Internet of Things systems.

Ansys secured an award in the category of Joint Development of 3nm Design Infrastructure for delivering [Ansys® RedHawk-SC™](#) and [Ansys® Totem™](#). These foundry-certified, state-of-the-art power integrity and electromigration signoff tools were optimized for TSMC's 3nm process technology, enabling customers to satisfy key power, thermal and reliability requirements for cutting-edge applications.

Additionally, Ansys earned an award in the category of Joint Development of 3D-IC Design Productivity Solution for providing [Ansys® RedHawk™](#), [Ansys® RedHawk-SC Electrothermal™](#) and [Ansys® RaptorH™](#). These advanced semiconductor analysis tools were certified for the latest variant of TSMC's high-speed, leading-edge CoWoS® and InFO 3D-IC packaging technologies, empowering customers to simulate and alleviate power and thermal reliability issues and to achieve optimal electrical performance.

"We're pleased to congratulate Ansys as the winner of two 2020 TSMC OIP Partner of the Year awards. These awards are a testament to their delivery of multiphysics simulation solutions that enable customer design success, benefitting from the significant power and performance boost of TSMC's latest and most advanced technologies," said Suk Lee, senior director of Design Infrastructure Management Division at TSMC. "Together, we will continue to overcome customers' design challenges and speed breakthrough silicon innovations with increased confidence."

"Mutual customers rely on Ansys' industry-leading simulation solutions to ensure maximum electronics system performance and reliability for next-generation system-on-chip architectures and groundbreaking 3D-IC design solutions," said John Lee, vice president and general manager at Ansys. "Receiving two TSMC OIP Partner of the Year awards for 3nm and 3DIC design solutions reflects our long-time role as a trusted signoff partner for TSMC's latest technologies and Ansys is committed to continuing that tradition, helping TSMC drive development of new silicon systems for highly innovative applications."

/ About Ansys

If you've ever seen a rocket launch, flown on an airplane, driven a car, used a computer, touched a mobile device, crossed a bridge or put on wearable technology, chances are you've used a product where Ansys software played a critical role in its creation. Ansys is the global leader in engineering simulation. Through our strategy of Pervasive Engineering Simulation, we help the world's most innovative companies deliver radically better products to their customers. By offering the best and broadest portfolio of engineering simulation software, we help them solve the most complex design challenges and create products limited only by imagination. Founded in 1970, Ansys is headquartered south of Pittsburgh, Pennsylvania, U.S.A. Visit www.ansys.com for more information.

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